

A DOCPHOENIX

## **OUTGOING**

CTMS
Miscellaneous Office Action
IMIS
Miscellaneous Internal Document
NRES
Letter Restarting Period for Response
1449
Signed 1449
892
892
Abandonment ABN
APDEC Board of Appeals Decision
APEA
Examiner Answer to Appeal Brief
CRFR
Letter Requiring CRF
CTAV
Count Advisory Action
CTEQ
Count Ex parte Quayle
CTFR
Count Final Rejection
CTNF
CTRS
EXIN
Examiner Interview
FOR
Foreign Reference
M903
DO/EO Acceptance
M905

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NFDR
Formal Drawing Required
NOA
Notice of Allowance
NPL
Non-Patent Literature
PEFN
Pre-Exam Formalities Notice
PETDEC
Petition Decision
ANE.I
After Final or 312 Amendment

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DO/EO Missing Requirement

CLMPTO
PTO Prepared Complete Claim Set

File Wrapper Issue Information

SRNT\_\_\_\_\_Examiner Search Notes
SRFW

File Wrapper Search Info

SEQREQ
Sequence Problem Att. from Examiner

\_\_\_CDCHECK\_\_\_\_

Compact Disk Review Checklist

9/15/03



# United States Patent and Trademark Office

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UNITED STATES DEPARTMENT OF COMMERCE United States Patent and Trademark Office Address: COMMISSIONER FOR PATENTS P.O. Box 1450 Alexandria, Virginia 22313-1450 www.uspto.gov

APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO	
10/021,782	12/18/2001	Cyrus E. Tabery	50432-293 1966		
20277 . 75	. 7590 12/08/2003		EXAMINER .		
	T WILL & EMERY		ISAAC, STA	NETTA D	
600 13TH STRI	EET, N.W. N, DC 20005-3096		ART UNIT	PAPER NUMBER	
			2812		
•			DATE MAILED: 12/08/200	3	

Please find below and/or attached an Office communication concerning this application or proceeding.

					M.
		Applica	tion No.	Applicant(s)	
Office Action Summary		10/021,	782	TABERY ET AL.	
		Examin	er	Art Unit	
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Period fo	The MAILING DATE of this commu or Reply	nication appears on t	he cover sheet with the	e correspondence ad	idress
THE I - External - If the - If NO - Failu - Any	ORTENED STATUTORY PERIOD MAILING DATE OF THIS COMMUI nsions of time may be available under the provision SIX (6) MONTHS from the mailing date of this conseperiod for reply specified above is less than thirty period for reply is specified above, the maximum resto reply within the set or extended period for repreply received by the Office later than three month and patent term adjustment. See 37 CFR 1.704(b).	NICATION.  Ins of 37 CFR 1.136(a). In no ending in the second statutory period will apply and only will, by statute, cause the a	event, however, may a reply be tatutory minimum of thirty (30) will expire SIX (6) MONTHS from the polication to become ABANDO	e timely filed days will be considered time rom the mailing date of this o	ly. communication.
1)🖾	Responsive to communication(s) f	led on 22 September	<u>- 2003</u> .		
2a)□	This action is FINAL.	2b)⊠ This action is	non-final.		
3)	Since this application is in conditional closed in accordance with the practice.				e merits is
Disposit	ion of Claims				
5)□ 6)⊠ 7)□	Claim(s) 1-14 is/are pending in the 4a) Of the above claim(s) is. Claim(s) is/are allowed. Claim(s) 1-14 is/are rejected. Claim(s) is/are objected to. Claim(s) are subject to rest	are withdrawn from o			
Applicat	ion Papers				
9)[	The specification is objected to by	he Examiner.			
10)	The drawing(s) filed on is/ar	e: a)∏ accepted or	b)□ objected to by th	ne Examiner.	
	Applicant may not request that any ob				
	Replacement drawing sheet(s) includi				
	The oath or declaration is objected	to by the Examiner.	Note the attached Off	ice Action of form P	10-152.
•	under 35 U.S.C. §§ 119 and 120				
a) 13)□ / s 3 4 14)□ /	Acknowledgment is made of a claim All b) Some * c) None of 1. Certified copies of the priori 2. Certified copies of the priori 3. Copies of the certified copie application from the International Cee the attached detailed Office act acknowledgment is made of a claim ince a specific reference was included Terminal Certified Certified copies application from the International Center of the act acknowledgment is made of a claim acknowledgment is made of a claim acknowledgment is made of a claim after the first set acts and the first set acknowledgment is made of a claim acknowledgm	y documents have be by documents have be s of the priority documents on all Bureau (PCT Resion for a list of the ce for domestic priority led in the first sentents anguage provisional anguage provisional	een received. een received in Application ments have been received at 17.2(a)). ertified copies not received under 35 U.S.C. § 11 ce of the specification application has been under 35 U.S.C. §§ 1	eation No eived in this National eived. 9(e) (to a provisional or in an Application received. 20 and/or 121 since	al application) n Data Sheet. e a specific
Attachmer	nt(s)				
2) Notice	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review mation Disclosure Statement(s) (PTO-1449)		· <u>—</u>	ary (PTO-413) Paper No al Patent Application (PT	- ·

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#### Response to Arguments

- 1. In view of the Appeal Brief filed on 09/22/03, PROSECUTION IS HEREBY REOPENED.
- 2. Applicant's arguments see REMARKS, filed 02/27/03, with respect to the rejection(s) of claim(s) 1-14 under 102 and 103 Rejections have been fully considered and are persuasive.

  Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of Yamazaki et al. US Patent 6,242,292.

### Claim Rejections - 35 USC § 102

3. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless –

(e) the invention was described in a patent granted on an application for patent by another filed in the United States before the invention thereof by the applicant for patent, or on an international application by another who has fulfilled the requirements of paragraphs (1), (2), and (4) of section 371(c) of this title before the invention thereof by the applicant for patent.

The changes made to 35 U.S.C. 102(e) by the American Inventors Protection Act of 1999 (AIPA) and the Intellectual Property and High Technology Technical Amendments Act of 2002 do not apply when the reference is a U.S. patent resulting directly or indirectly from an international application filed before November 29, 2000. Therefore, the prior art date of the reference is determined under 35 U.S.C. 102(e) prior to the amendment by the AIPA (pre-AIPA 35 U.S.C. 102(e)).

4. Claims 1,3-6,8-14 are rejected under 35 U.S.C. 102(e) as being anticipated by Yamazaki et al. US Patent 6,242,292.

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5. <u>Yamazaki</u> discloses a semiconductor method substantially as claimed. See **FIGS. 1-6B** where <u>Yamazaki</u> teaches a method of manufacturing a semiconductor device, comprising the steps of:

forming a gate electrode over a substrate; (See col. 9 lines 26-50)

introducing ions into the substrate 11 to form source/drain regions (51, 52) in the substrate proximate to the gate electrode;

activating a portion of the source/drain regions by laser thermal annealing using a laser; (See col. 9 lines 26-50)

moving the laser and the substrate relative to one another; and (See col. 6 lines 3-45) activating another portion of the source/drain regions by laser thermal annealing using the laser,

wherein the movement of the laser and the substrate relative to one another is continuous between and during the steps of activating the portion of the source/drain regions and activating the other portion of the source/drain regions. (See col. 9 lines 26-50)

- 6. Pertaining to claim 3, <u>Yamazaki</u> teaches the invention according to claim 1, wherein each portion of the source/drain regions receives more than one single pulse of energy from the laser. (See **col.** 7 lines 1-63)
- 7. Pertaining to claim 5, <u>Yamazaki</u> teaches the invention according to claim 1, wherein a spot area of the laser on the substrate is less than 50 millimeters<sup>2</sup>.
- 8. Pertaining to claim 6, <u>Yamazaki</u> teaches a method of manufacturing a semiconductor device, comprising the steps of:

forming a gate electrode over substrate;

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introducing ions into the substrate to form source/drain regions in the substrate proximate to the gate electrode;

activating a portion of the source/drain regions by laser thermal annealing using a laser; moving the laser and the substrate relative to one another; and

activating another portion of the source/drain regions by laser thermal annealing using the laser,

wherein a spot area of the laser on the substrate is less than 50 millimeters<sup>2</sup> (See col. 3 lines 24-25 where the linear beam of 1mm width and 125 mm length is equal 12.5 mm<sup>2</sup>)

- 9. Pertaining to claim 8, <u>Yamazaki</u> teaches the invention according to claim 6, wherein each portion of the source/drain regions receives more than one single pulse of energy from the laser. (See col. 7 lines 1-63)
- 10. Pertaining to claims 4, 8, 9 and 12, <u>Yamazaki</u> teaches the invention according to claim 8, wherein each pulse from the laser respectively irradiates non-identical portions of the source/drain regions. (See col. 7 lines 1-63)
- 11. Pertaining to claim 10, <u>Yamazaki</u> teaches the invention according to claim 6, wherein the laser and the substrate move relative to one another at a constant velocity.
- 12. Pertaining to claim 11, <u>Yamazaki</u> teaches a method of manufacturing a semiconductor device, comprising the steps of:

forming a gate electrode over a substrate; introducing ions into the substrate to form source/drain regions in the substrate proximate to the gate electrode;

activating a portion of the source/drain regions by laser thermal annealing using a pulse of laser energy from a laser; moving the laser and the substrate relative to one another; and

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activating another portion of the source/drain regions by laser thermal annealing using another pulse of laser energy from the laser,

wherein the laser and the substrate move relative to one another after each pulse of laser energy and each portion of the source/drain regions receives more than one single pulse of energy from the laser.

- 13. Pertaining to claim 13, <u>Yamazaki</u> teaches the invention according to claim 11, wherein a spot area of the laser on the substrate is less than 50 millimeters<sup>2</sup>.
- 14. Pertaining to claim 14, <u>Yamazaki</u> teaches the invention according to claim 11, wherein the laser and the substrate move relative to one another at a constant velocity. (See **col. 6 lines 3-45**)

### Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 2 and 7are rejected under 35 U.S.C. 103(a) as being unpatentable over rejected under 35 U.S.C. 103(a) as being unpatentable over Yamazaki et al. Patent Number 6,242,292 in view of prior art
- 3. Claims 2 and 7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamazaki et al. Patent Number 6,242,292 in view of prior art.
- 4. Pertaining to claims 2 and 7, Yamazaki fails the invention according to claim 1, wherein each portion of the source/drain regions receives no more than one single pulse of energy from